- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

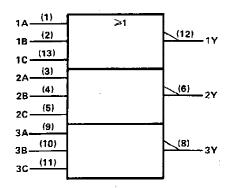
These devices contain three independent 3-input NOR gates.

The SN5427 and SN54LS27 are characterized for operation over the full military temperature range of  $-55\,^{\circ}\text{C}$  to 125  $^{\circ}\text{C}$ . The SN7427 and SN74LS27 are characterized for operation from 0  $^{\circ}\text{C}$  to 70  $^{\circ}\text{C}$ .

### FUNCTION TABLE (each gate)

	NPUT	s	OUTPUT
Α	В	С	Y
Н	х	x	Ļ
Х	Н	х	L
X	Х	Н	L
L	L	L	н

### logic symbol†



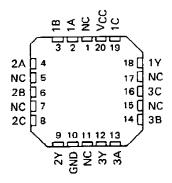
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5427, SN54LS27...J OR W PACKAGE SN7427...N PACKAGE SN74LS27...D OR N PACKAGE (TOP VIEW)

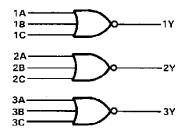
1 A □	1	U14 D VCC
1B 🗖	2	13 <u> </u> ] 1C
2A 🗆	3	12 <b> </b> ] 1Y
2B 🗖	4	11D 3C
2C 🗖	5	10 3B
2Y 🗖	6	9 🛚 3A
GND 🗖	7	8 🗖 3 Y

SN54LS27 . . . FK PACKAGE (TOP VIEW)



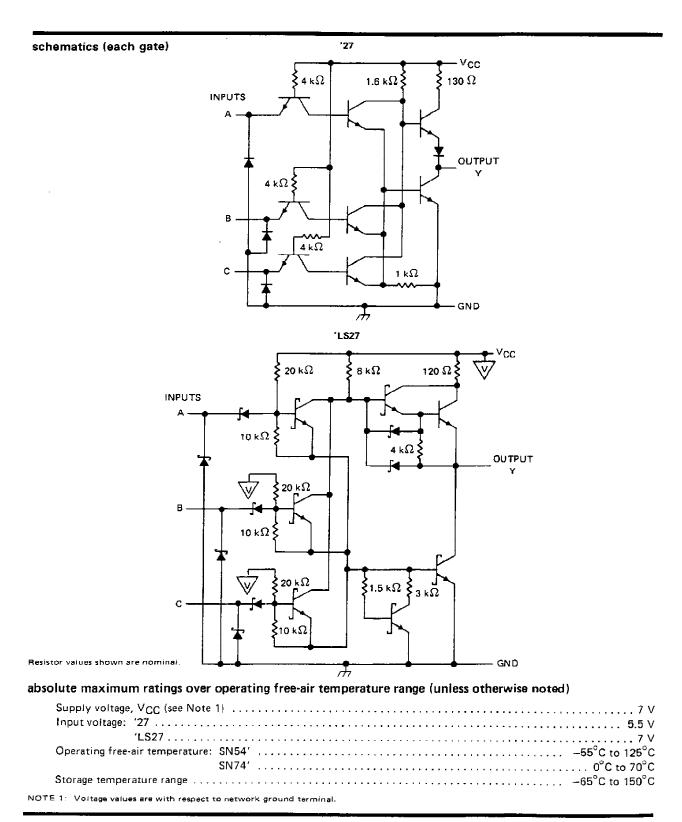
NC - No internal connection

### logic diagram



### positive logic

 $Y = \overline{A + B + C}$  or  $Y = \overline{A \cdot B \cdot C}$ 



## recommended operating conditions

			SN5427				SN7427			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
VGC	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧		
$V_{IH}$	High-level input voltage	2	•		2			٧		
VIL	Low-level input voltage			8,0			0.8	٧		
Іон	High-level output current			- 0.8			- 0.8	mΑ		
lo L	Low-level output current			16			16	mΑ		
TA	Operating free-air temperature	- 55		125	0		70	°c		

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	-	TEST CONDIT	TIONS +		SN5427	,		SN7427	,	UNIT			
FANAMETER		rest conditi	TIONS	MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	UNIT			
Vικ	V <sub>CC</sub> = MIN,	I <sub>1</sub> = - 12 mA				<b>– 1.5</b>			- 1.5	٧			
۷ОН	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = 0.8 V,	I <sub>OH</sub> = -0.8 mA	2.4	3.4		2.4	3.4	i	V			
۷٥٢	VCC = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 16 mA	<b></b>	0.2	0.4		0.2	0.4	٧			
l <sub>I</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V				1			1	mA			
ήн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V			•	40			40	μΑ			
կլ	VCC = MAX,	V1 = 0.4 V				- 1.6			- 1.6	mΑ			
los §	V <sub>CC</sub> = MAX			- 20		- 55	- 18		- 55	mA			
ІССН	VCC = MAX,	VI = 0 V	<del> </del>		10	16		10	16	mA			
<sup>I</sup> CCL	V <sub>CC</sub> = MAX,	See Note 2			16 ,	26		16	26	mA			

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

# switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONI	OITIONS	MIN	TYP	MAX	UNIT
tPLH	A, B or C	v	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF		10	15	ns
tpHL	A, B UI C	,	11[ - 400 32,	C[ - 10 h		7	11	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . § Not more than one output should be shorted at a time.

# SN54LS27, SN74LS27 TRIPLE 3-INPUT POSITIVE-NOR GATES

#### recommended operating conditions

•		S	SN54LS27			SN74LS27			
_		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			٧	
VIL	Low-level input voltage			0.7			0.8	٧	
Іон	High-level output current			- 0.4			- 0.4	mΑ	
loL	Low-level output current			4			В	mA	
Тд	Operating free-air temperature	<b>– 55</b>		125	0		70	°c	

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS †				27	S	N74LS2	7	LIBUAT
PARAMETER		TEST CONDI	HOM2 T	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	TINU
۷ıĸ	V <sub>CC</sub> = MIN,	I <sub>I</sub> = - 18 mA				<b>– 1.5</b>			<b>– 1.5</b>	>
Voн	V <sub>CC</sub> - MIN,	V <sub>IL</sub> = MAX,	I <sub>OH</sub> = − 0.4 mA	2.5	3.4		2.7	3.4		٧
.,	VCC = MIN,	V <sub>1H</sub> = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOL = 8 mA					0.35	0.5	
l <sub>l</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
ин	VCC = MAX,	V <sub>1</sub> = 2.7 V				20			20	μΑ
l(L	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	*			- 0.4			0.4	mA
IOS §	V <sub>CC</sub> = MAX			- 20		- 100	20		- 100	mA
Іссн	V <sub>CC</sub> = MAX.	V <sub>I</sub> = 0 V			2	4		2	4	mΑ
lccr	VCC = MAX.	See Note 2			3.4	6.8		3.4	6.8	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
tPLH	A B == C	<b>,</b>	R <sub>L</sub> = 2 kΩ,	C <sub>1</sub> = 15 pF		10	15	пѕ
t <sub>PHL</sub>	A, B or C	, 	n 2 ksz,	C[ - 15 pF		10	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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## **PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
JM38510/30302B2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302B2A
JM38510/30302B2A.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302B2A
JM38510/30302B2A.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302B2A
JM38510/30302BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
JM38510/30302BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
JM38510/30302BCA.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
JM38510/30302BCA.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
JM38510/30302BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA
JM38510/30302BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA
JM38510/30302BDA.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA
JM38510/30302BDA.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA
M38510/30302B2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302B2A
M38510/30302B2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302B2A
M38510/30302BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
M38510/30302BCA	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BCA
M38510/30302BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA





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Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)	
M38510/30302BDA	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30302BDA	
SN54LS27J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS27J	
SN54LS27J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS27J	
SN54LS27J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS27J	
SN54LS27J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS27J	
SN74LS27D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	LS27	
SN74LS27D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	LS27	
SN74LS27DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	
SN74LS27DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	
SN74LS27DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	
SN74LS27DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS27	
SN74LS27N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS27N	
SN74LS27N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS27N	
SN74LS27N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS27N	
SN74LS27N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS27N	
SN74LS27NSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	
SN74LS27NSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	
SN74LS27NSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	
SN74LS27NSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS27	
SNJ54LS27FK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 27FK	
SNJ54LS27FK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 27FK	
SNJ54LS27FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 27FK	
SNJ54LS27FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 27FK	
SNJ54LS27J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27J	
SNJ54LS27J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27J	
SNJ54LS27J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27J	
SNJ54LS27J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27J	

-55 to 125

-55 to 125

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SNJ54LS27W

SNJ54LS27W

SNJ54LS27W.A

SNJ54LS27W.A

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Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	, ,	``				(4)	(5)		` '
SNJ54LS27W	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27W
SNJ54LS27W	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS27W

No

No

**SNPB** 

**SNPB** 

N/A for Pkg Type

N/A for Pkg Type

25 | TUBE

25 | TUBE

Active

Active

Production

Production

CFP (W) | 14

CFP (W) | 14

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF SN54LS27, SN74LS27:

Catalog: SN74LS27

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# PACKAGE OPTION ADDENDUM

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Military: SN54LS27

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS27DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS27NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS27DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS27NSR	SOP	NS	14	2000	353.0	353.0	32.0



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### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30302B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30302B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30302BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30302BDA.A	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30302B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30302BDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS27N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS27N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS27N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS27N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS27FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS27FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS27W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS27W.A	W	CFP	14	25	506.98	26.16	6220	NA



SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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